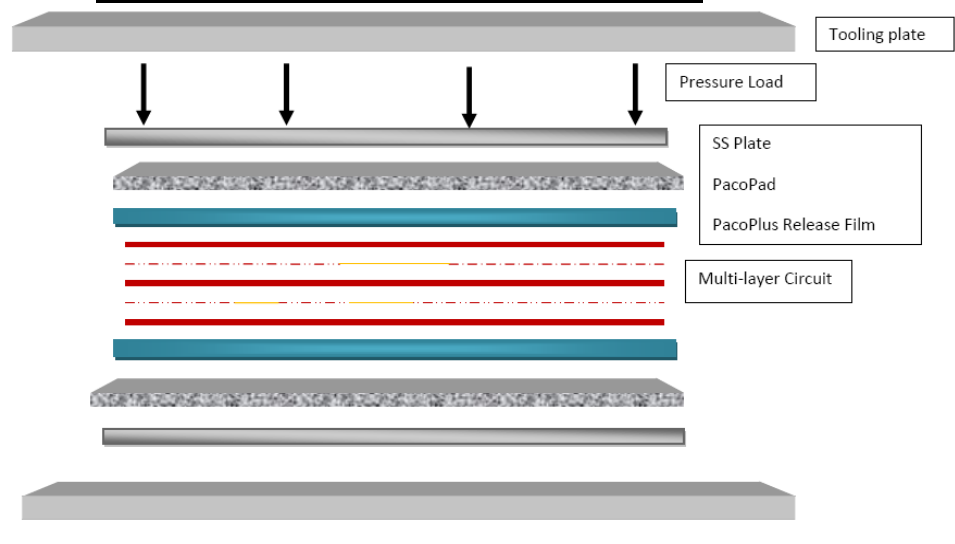


TECHNICAL DATA SHEET

PRODUCT:

PACOPADS® are specifically engineered to improve the process of laminating rigid multi-layer and flexible printed circuit boards. It serves two functions: To help accurately control heat rise and to insure maximum “Z” axis pressure distribution. It provides a soft make up to equalize the pressure applied across the panel surface. The nature of lamination introduces variables and inconsistency related to high and low pressure spots. The soft make-up and predictable compression value of Pacopads introduces macro Z-Axis pressure distribution providing a best practice environment to improve product yields. Thickness consistency and dimensional stability of finished circuits will improve as it relates to your lamination process. Pacopads are a better alternative to Kraft Paper, Reinforced Rubber or other hard Polymer re-useable products which all offer only limited Z-Axis pressure distribution. They can be matched to previous lamination profiles as they are available in thickness of .035” and .055”.

RECOMMENDED LAMINATION LAY-UP:



TECHNICAL DATA:

Physical Property	Test Method	Reported Units	Typical Values
Max. Application Temp.	Q 1025	°F (°C)	475°F(246°C)
Gauge	T-411	in	0.0550 ± 10 %
Density	T-410 and T411	Lb/in	4.5
Tensile (MD)	T-494	Lb/in	≤ 10
Brightness	T-452	%	85.0
Compression	ASTM F806-88	%	40.0

SHELF LIFE AND STORAGE:

- Material should be kept dry and in a clean room below 113°F (45°C)